# **<b>&TDK** Multilayer Ceramic Chip Capacitors

#### C3216X5R1E336M160AC



#### TDK item description C3216X5R1E336MT\*\*\*\*

Applications	Commercial Grade
Feature	General General (Up to 50V)
Series	C3216 [EIA 1206]
Status	Production



	Size
Length(L)	3.20mm ±0.20mm
Width(W)	1.60mm ±0.20mm
Thickness(T)	1.60mm ±0.20mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	1.00mm Min.
Recommended Land Pattern (PA)	2.10mm to 2.50mm(Flow Soldering)
	2.00mm to 2.40mm(Reflow Soldering)
Recommended Land Pattern (PB)	1.10mm to 1.30mm(Flow Soldering)
	1.00mm to 1.20mm(Reflow Soldering)
Recommended Land Pattern (PC)	1.00mm to 1.30mm(Flow Soldering)
	1.10mm to 1.60mm(Reflow Soldering)

Electrical Characteristics		
Capacitance	33µF ±20%	
Rated Voltage	25VDC	
Temperature Characteristic	X5R(±15%)	
Dissipation Factor (Max.)	10%	
Insulation Resistance (Min.)	3MΩ	

	Other
Soldering Method	Wave (Flow)
	Reflow
AEC-Q200	No
Packing	Blister (Plastic)Taping [180mm Reel]
Package Quantity	2000pcs

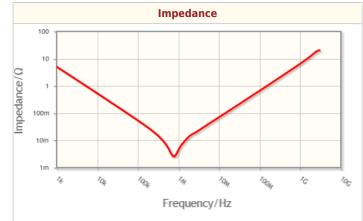
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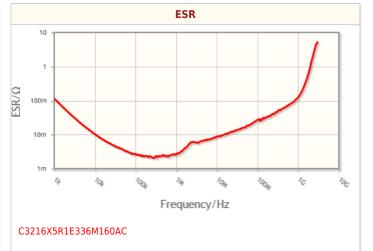
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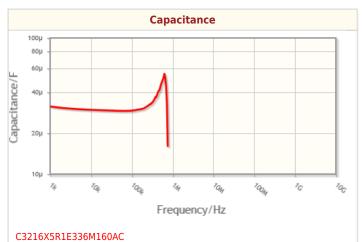


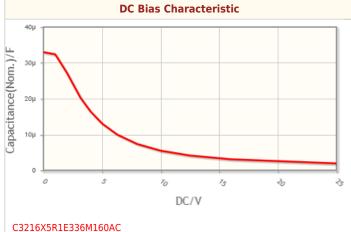


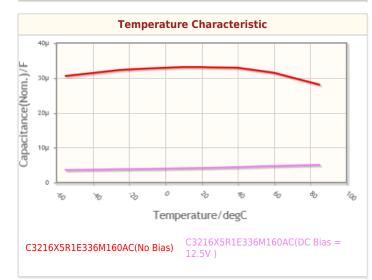
### Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

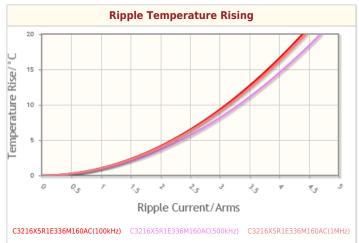


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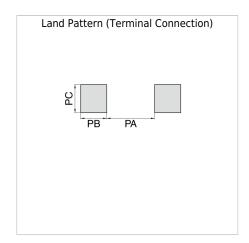
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## Associated Images



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